



US00D411193S

United States Patent [19] Oba

[11] **Patent Number: Des. 411,193**

[45] **Date of Patent: ** Jun. 22, 1999**

[54] **PLAYER FOR SEMICONDUCTOR ELEMENT**

[75] Inventor: **Haruo Oba**, Tokyo, Japan

[73] Assignee: **Sony Corporation**, Tokyo, Japan

[**] Term: **14 Years**

[21] Appl. No.: **29/079,667**

[22] Filed: **Nov. 20, 1997**

[30] **Foreign Application Priority Data**

May 21, 1997 [JP] Japan 9-55009

[51] **LOC (6) Cl.** **14-99**

[52] **U.S. Cl.** **D14/124**

[58] **Field of Search** D14/105, 109,
D14/124, 160; 174/52.1; 361/684, 686-689,
737, 753

[56] **References Cited**

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Primary Examiner—Brian N. Vinson
Attorney, Agent, or Firm—Foley & Lardner

[57] **CLAIM**

The ornamental design for a player for semiconductor element, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a player for semiconductor element showing our new design;
FIG. 2 is a top plan view thereof;
FIG. 3 is a left side elevational view thereof;
FIG. 4 is a front elevational view thereof;
FIG. 5 is a bottom plan view thereof;
FIG. 6 is a right side elevational view thereof; and,
FIG. 7 is a rear elevational view thereof.

1 Claim, 3 Drawing Sheets

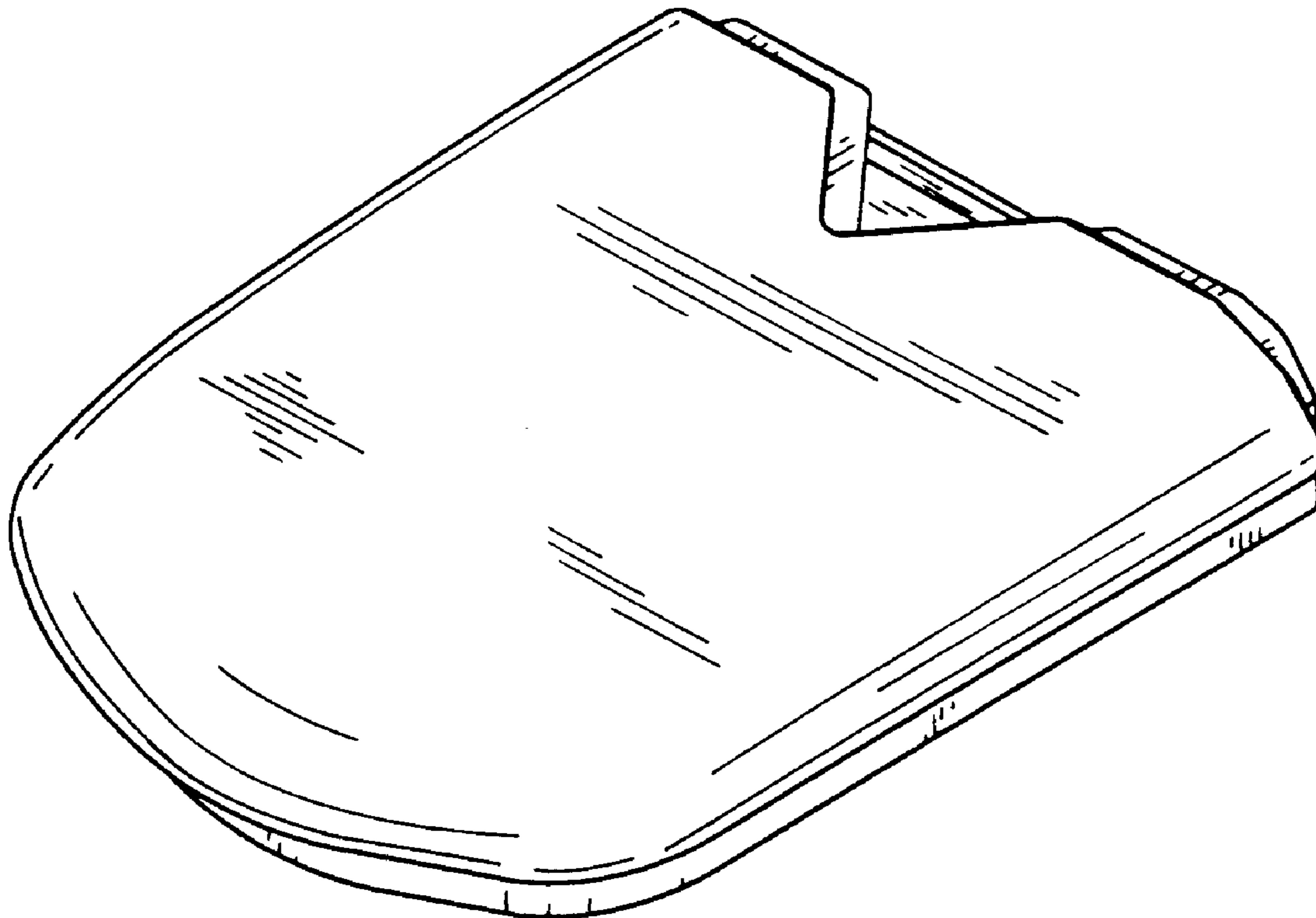


FIG. 1

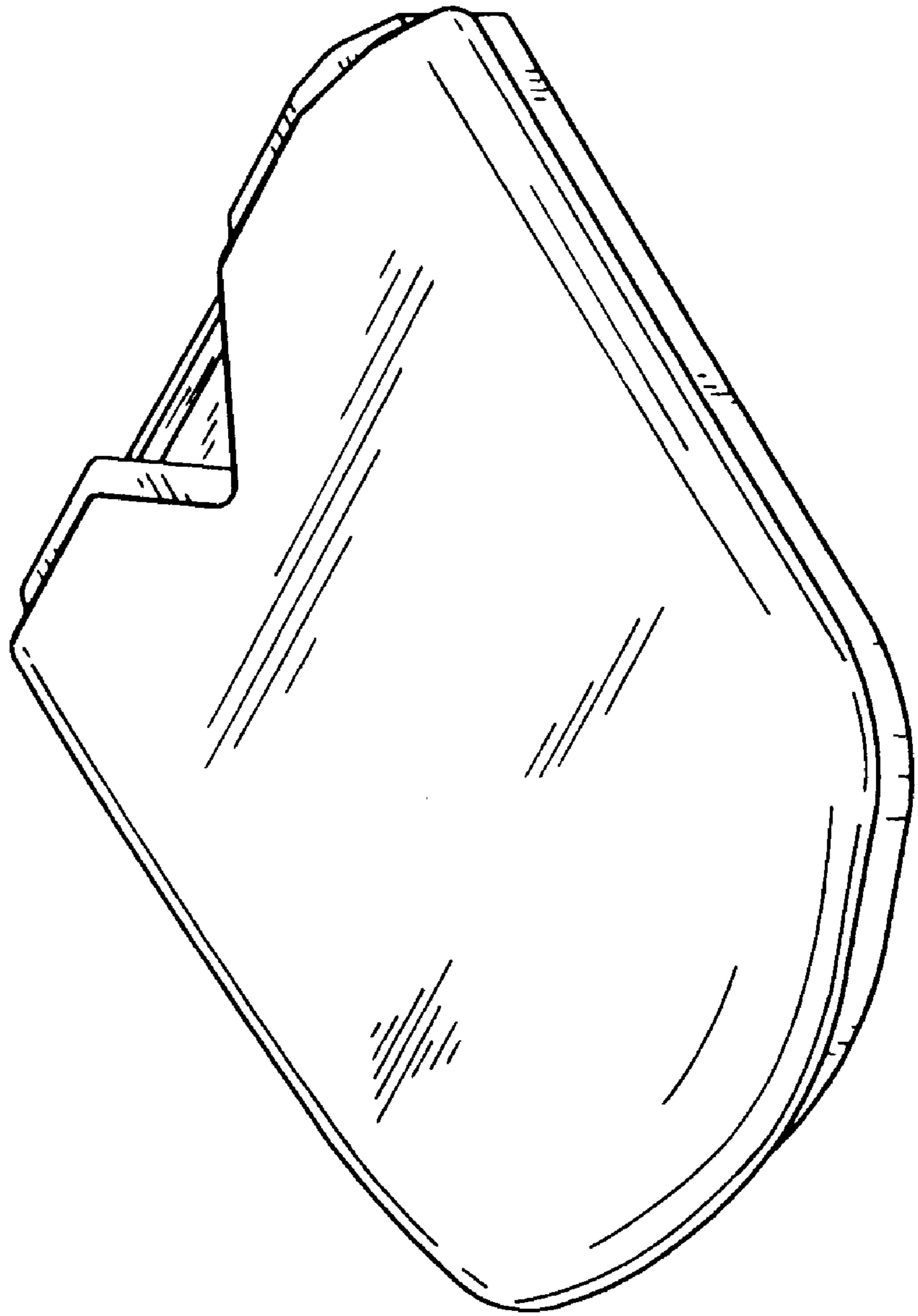


FIG. 2

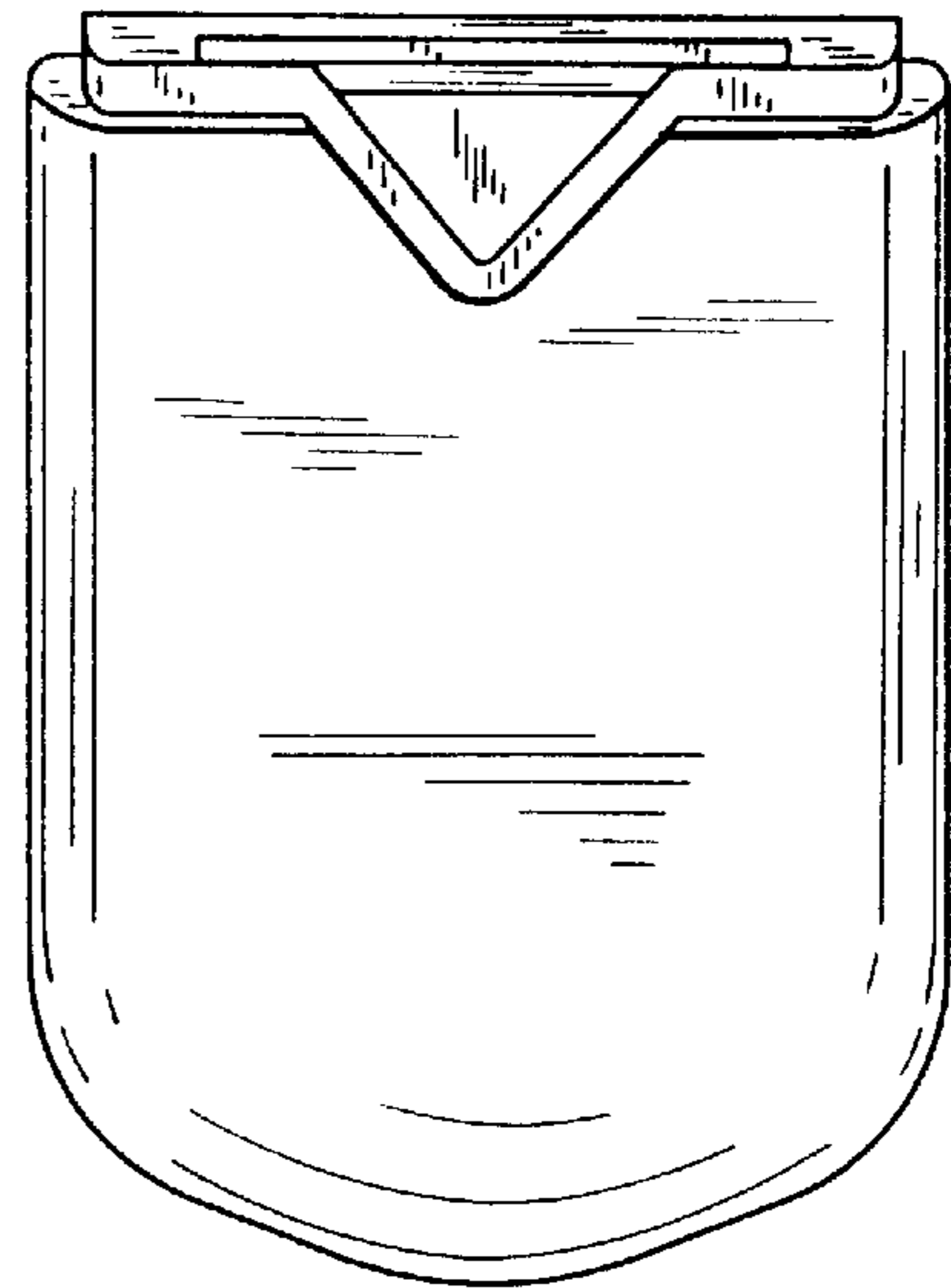


FIG. 3

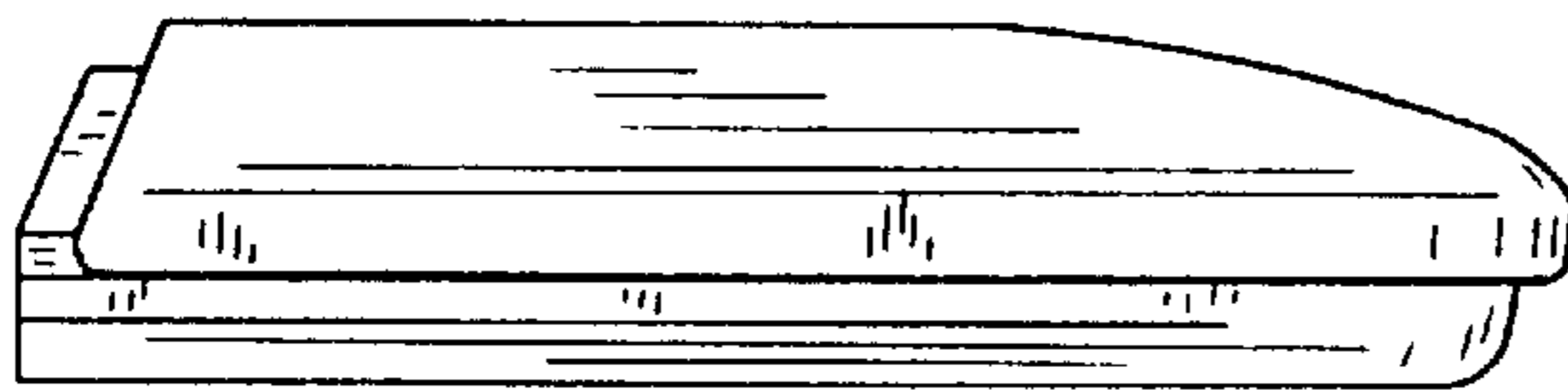


FIG. 4

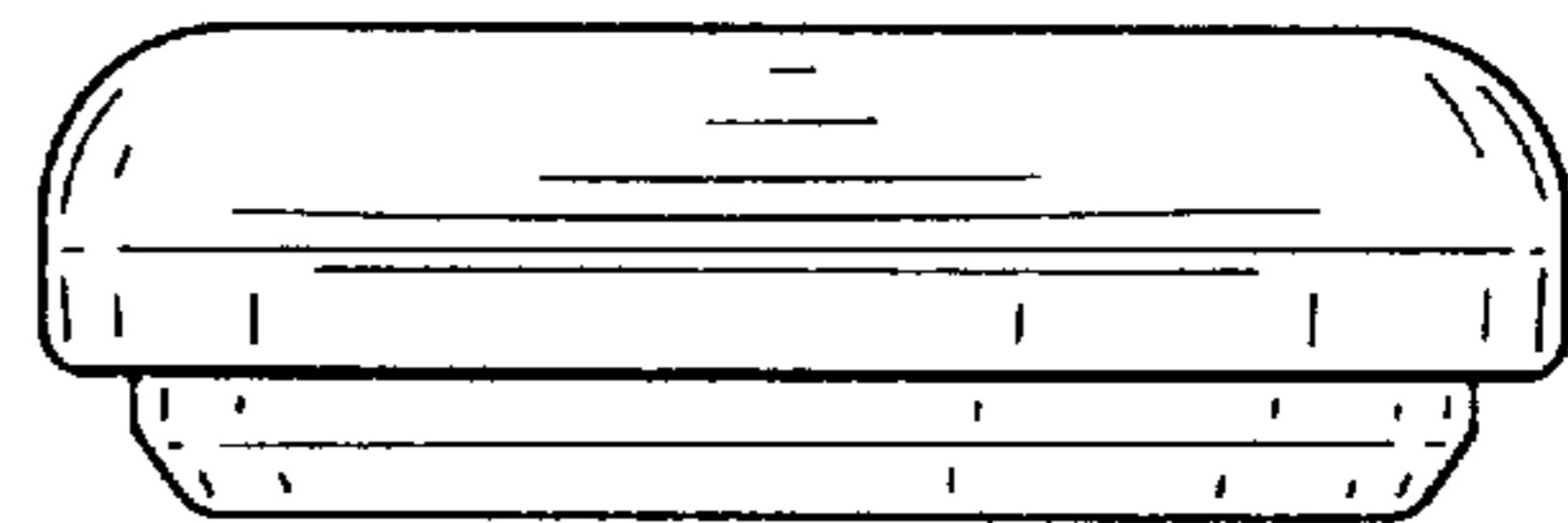


FIG. 5

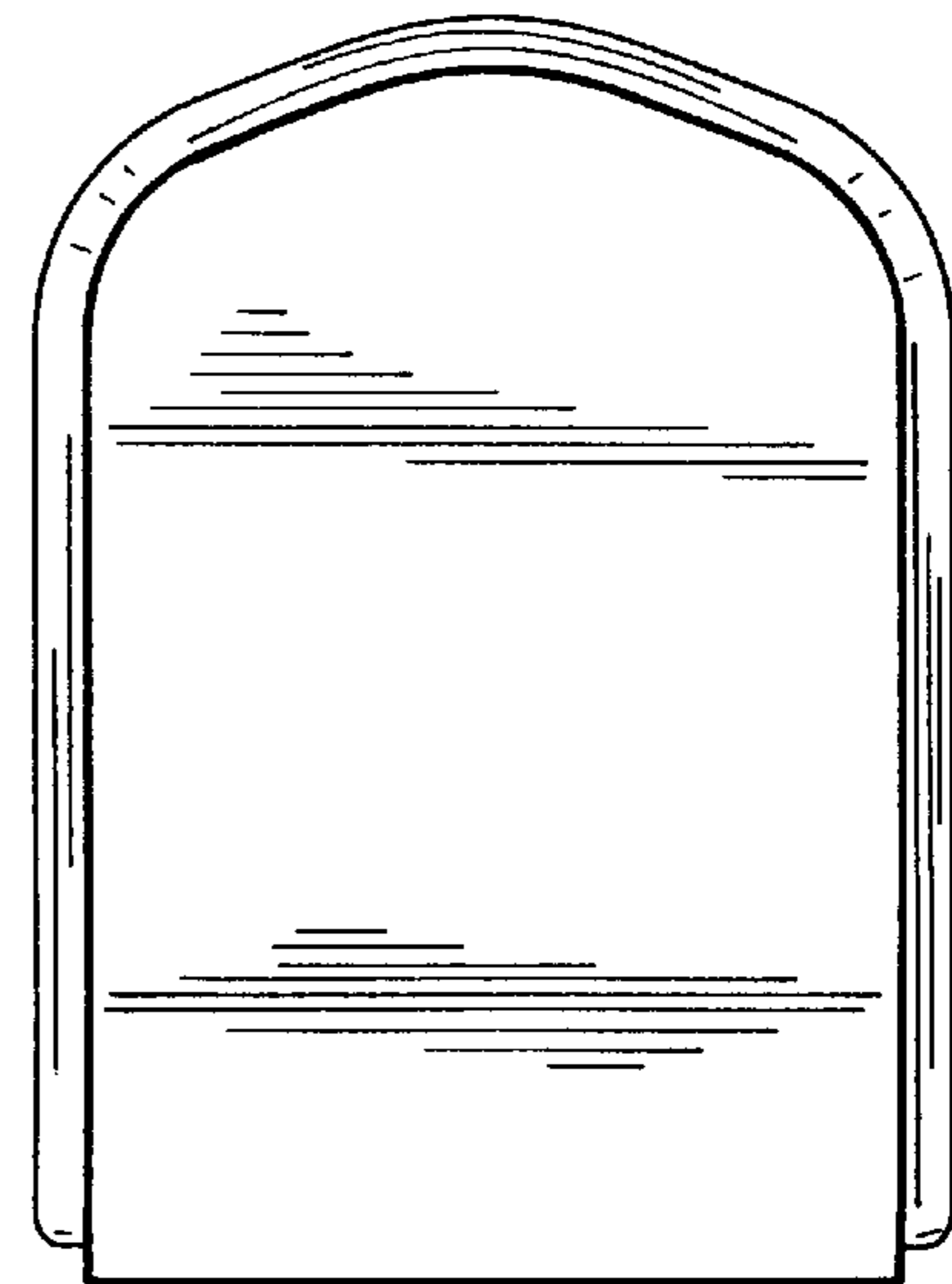


FIG. 6

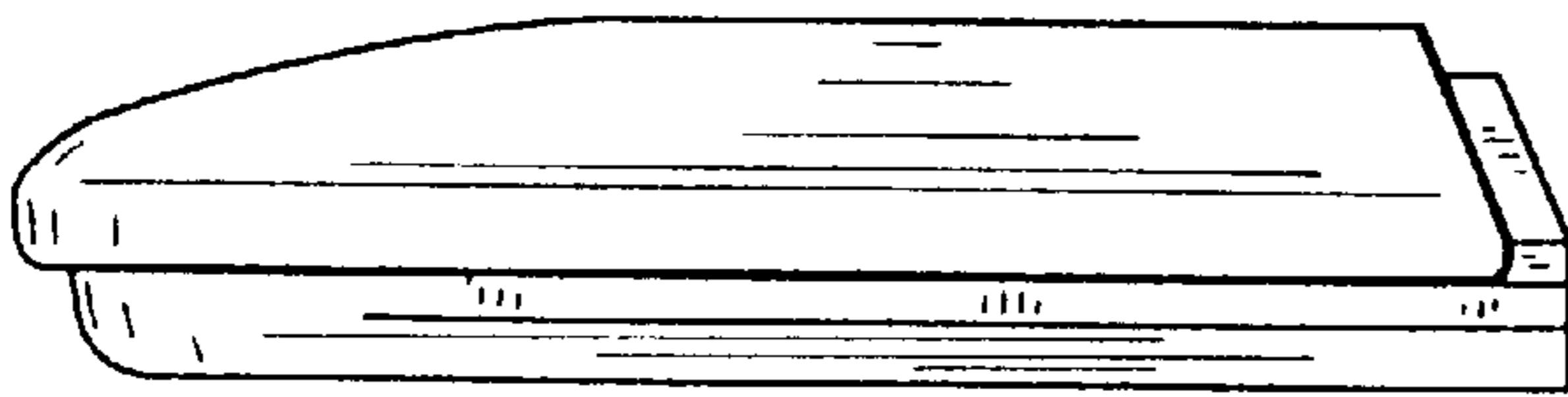


FIG. 7

